CLAIMS

1. An etchant composition for etching of a layer to be etched that contains molybdenum film,

the etchant composition comprising an etching inhibitor, an acid including a phosphoric acid, an acetic acid, and a nitric acid, and water and having a pH of 1 or less,

wherein the etching inhibitor is polyalkyleneimine having an average molecular weight of 1,200 or more and 3,000 or less,

a blending amount of the etching inhibitor is 0.1% by mass or more and 5% by mass or less.

2. The etchant composition according to claim 1, wherein the etchant composition does not contain hydrogen peroxide.

3. The etchant composition according to claim 1 or 2, wherein a zeta potential of a surface of the molybdenum film contained in the layer to be etched is a negative value, provided that the pH is 1 or less.

4. An etching method comprising:

etching a layer to be etched that contains molybdenum film with the etchant composition according to any one of claims 1 to 3.

5. The etching method according to claim 4, wherein a zeta potential of a surface of the molybdenum film contained in the layer to be etched is a negative value, provided that the pH is 1 or less.